

**ETCHING LIQUID FOR POLYIMIDE RESIN AND ETCHING METHOD**

Patent Number: JP5202206  
Publication date: 1993-08-10  
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Requested Patent: ☐ JP5202206  
Application Number: JP19910256803 19911003  
Priority Number(s):  
IPC Classification: C08J7/00; H05K3/00  
EC Classification:  
Equivalents:

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**Abstract**

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**PURPOSE:** To accurately etch at a sufficiently high rate a polyimide resin obtained from biphenyltetracarboxylic dianhydride and a diamine through polycondensation.  
**CONSTITUTION:** A polyimide resin is etched at 60-90 deg.C with an etchant comprising 20-70vol.% aqueous sodium hydroxide solution (40wt.%), 2-20vol.% ethylenediamine, 10-30vol.% hydrazine monohydrate, 2-10vol.% dimethylamine solution (20wt.%), and 2-10vol.% N,N-dimethylformamide.

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